



2026 Asia-Pacific Microwave Conference

APMC2026

Dates: November 8(Sun.)-11(Wed.), 2026

Venue: Fukuoka International Congress Center

Exhibition and Sponsorships prospectus

- Exhibition
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- Item Sponsor
- Sponsorship Package

Organized by



The Institute of Electronics, Information
and Communication Engineers (IEICE) of Japan

Operational Management by



Nikkan Kogyo Communications, Inc.



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Dates: November 8–11, 2026 Venue: Fukuoka Convention Center

Chair's Message: Exhibition and Sponsorship Opportunities

Kenjiro NISHIKAWA, Kagoshima University

The 2026 Asia-Pacific Microwave Conference (APMC 2026) will be held from November 8 (Sunday) to November 11 (Wednesday), 2026, and is a premier international conference dedicated to the advancement of microwave and millimeter-wave engineering, encompassing both fundamental research and industrial applications throughout the Asia-Pacific region.

APMC is internationally recognized as one of the world's leading microwave conferences, together with the IEEE MTT-S International Microwave Symposium (IMS) and European Microwave Week (EuMW). The conference has long served as a key global forum for researchers, engineers, and industry professionals to present innovations, exchange technical knowledge, and promote international collaboration in microwave and related technologies.

APMC2026 will be organized under the conference concept:

"Microwave Innovation from Kyushu as Japan's Historical Gateway."

Kyushu has historically played a vital role as Japan's gateway for international exchange, fostering connections between Japan and the global community through technology, industry, and culture. Today, the region continues to be a center of excellence in advanced research and industrial development, particularly in microwave and millimeter-wave devices, semiconductors, wireless communications, measurement technologies, and emerging application areas such as 6G, quantum technologies, space systems, and IoT.

During the conference period, a Technical Exhibition will be held in conjunction with APMC 2026, providing an excellent opportunity for companies to present their latest products, technologies, and solutions related to microwave and millimeter-wave systems, components, materials, measurement and evaluation equipment, design and simulation tools, and system-level applications. The exhibition will attract a broad international audience, including researchers, engineers, and R&D professionals from academia, industry, and government laboratories.

In addition to exhibition opportunities, APMC 2026 invites companies and organizations to participate as Conference Sponsors. Sponsorship offers high visibility and recognition among an international audience, strengthens corporate presence within the global microwave community, and directly supports the success of the conference. Sponsors will benefit from enhanced exposure through conference materials, on-site signage, official publications, and digital platforms, as well as privileged opportunities for engagement with conference participants.

Participation as an Exhibitor and/or Sponsor of APMC 2026 provides a unique platform to promote your organization's technologies, expand international networks, foster collaboration with leading experts, and explore future business and research partnerships within the rapidly evolving microwave and millimeter-wave ecosystem.

We cordially invite your organization to join APMC 2026 as an exhibitor and/or sponsor and to support our mission of advancing microwave innovation from Kyushu to the global community. We sincerely look forward to your participation and contribution to the success of APMC 2026.

Conference Topics

Active Devices and Circuits

Low-noise devices and circuits / High-power devices and circuits / Wide band-gap semiconductor devices / Microwave tubes / Control circuits (mixers, oscillators, switches, etc.) / MMICs and RFICs / Millimeter-wave and terahertz (THz) integrated circuits / Graphene and other emerging material-based devices / Rectennas and RF energy conversion circuits

Passive Components

Passive components and circuits (couplers, hybrids, and divider s/combiners) / Planar and non-planar resonators, filters, and multiplexers / Waveguides and transmission lines / Ferrite components, SAW devices, RF MEMS / LTCC devices / Packaging and manufacturing techniques / Metamaterials and metasurfaces / Plasmonic, photonic, and optical components

Field Analysis, Simulation and Characterization

Electromagnetic field theory / Analytical methods and numerical techniques / CAD and optimization algorithms / Multiphysics modeling and simulation techniques / Interaction of EM waves with materials and tissues / Measurement techniques and systems (RF to THz) / Electromagnetic compatibility (EMC) and interference mitigation

Antennas and Propagation

Antenna theory and design / Microwave and millimeter-wave antennas / Sub-THz, THz, and optical antennas / Broadband and multi-band antennas / Small antennas / Array, reflectarrays, reconfigurable, adaptive, and smart antennas / MIMO antenna systems / Digital beamforming and multi-beam systems / Propagation and scattering analysis / Wireless channel modeling and characterization / Antenna measurements techniques

Microwave, Millimeter-Wave, and THz Systems and Applications

Microwave and millimeter-wave system design / Sub-THz and THz system implementations / MIMO and massive MIMO systems / Sensing, IoT, M2M and RFID systems / Near-field communication (NFC) systems / Microwave photonic components and systems / Radar, imaging, and detection systems / Software-defined, cognitive, and smart radio systems / Satellite communication systems / Wearable devices and systems / Mobility systems and intelligent transportation applications

Emerging Technologies and Applications

Beyond 5G, and 6G systems / Space applications and systems / Artificial intelligence (AI) and machine learning (ML) in microwave and EM design / Wireless power transfer (WPT) systems / Energy harvesting devices and systems / Quantum technologies / Microwave superconductivity technologies / Cryogenic technologies / Biological and healthcare applications of microwaves / Health monitoring and diagnostic systems / Microwave heating and chemistry applications / Nanomaterials and nanostructures / Green, low-carbon, and sustainable microwave technologies

APMC2026 Committee Officers

International Steering Committee

Atsushi SANADA
The University of Osaka

APMC Japan National Committee

Tadashi KAWAI
University of Hyogo

Steering Committee

Kenjiro NISHIKAWA
Kagoshima University

General Affairs Committee

Yasunori SUZUKI
Okayama Prefectural University

Technical Program Committee

Ryo ISHIKAWA
The University of Electro-Communications

Finance Committee

Tomohiko MITANI
Kyoto University

Local Arrangements Committee

Haruichi KANAYA
Kyushu University

Registration Committee

Hirokichi YOSHIKAWA
Kyocera Corporation

Ceremony Committee

Ramesh POKHAREL
Binghamton University

Publicity Committee

Kaoru SUDO
Murata Manufacturing Co., Ltd.

Publication Committee

Hiroaki IKEUCHI
Toshiba Corporation

Exhibition Committee

Tsunayuki YAMAMOTO
NIT, Tsuyama College

About Exhibition

Dates Nov. 8(Sun.) 12:00pm~5:00pm
Nov. 9(Mon.) 9:30am~5:00pm
Nov. 10(Tue.) 9:30am~5:00pm
Nov. 11(Wed.) 9:30am~3:00pm

Move-in & Installation Nov. 7(Sat.) 4:00pm~5:00pm
Nov. 8(Sun.) 9:00am~12:00pm

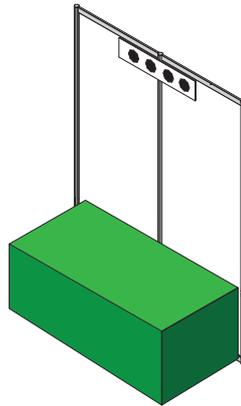
Dismantling & Move-out Nov. 11(Wed.) 3:00pm~4:30pm

Application DEADLINE
October 2 (Fri.), 2026

Venue Multi-Purpose Hall, Fukuoka International Congress Center

Exhibition Fee
200,000JPY (Excluding Tax)

A dedicated lounge area will be set up within the exhibition venue for relaxation and networking. While we will provide coffee, the space is also open for you to enjoy your own lunch.

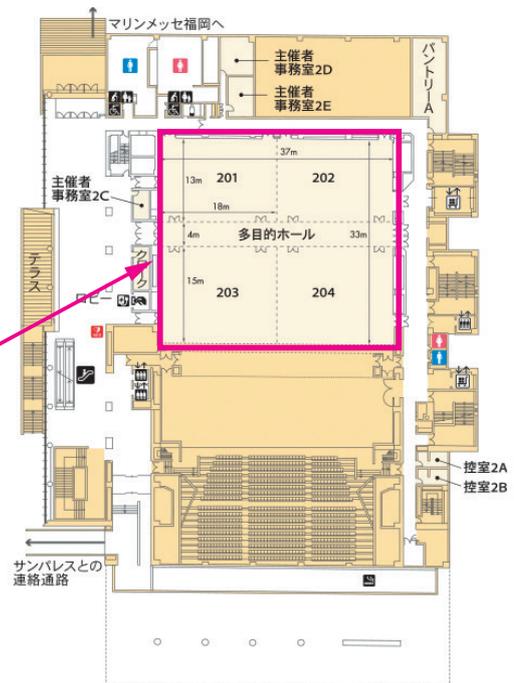
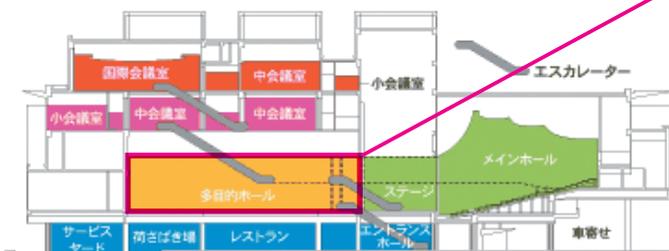


Equipment and other items included in the Exhibition Fee

Booth size	W1980×D900×H2400mm
Company name sign	1
Table	1 (W1800×D900×H700mm)
Chair	1
Electricity	available for PC

*For additional electrical capacity or optional items such as catalog stands and spotlights, please contact.

Exhibition Layout



Application
DEADLINE
September
8 (Tue.),
2026

Conference Sponsorship

Sponsorship Packages	Fee (Tax excl.)	Benefits						
		Exhibition	Web Banner ad	Logo placement on Conference Bag	Logo placement on Coffee break Signboard	Logo placement on Reception Signboard	Logo placement on Banquet Signboard	Complimentary Conference registration
Diamond	1,000,000JPY	1	○ (Large)	○	○	○	○	3
Platinum	800,000JPY	1	○ (Large)	○	-	○	○	2
Gold	400,000JPY	1	○ (Small)	○	-	-	-	1

Banner Ad on the official website

Banner advertisement opportunities are available on the APMC2026 official website.

- Banner Ad(Large): 150,000JPY
- Banner Ad(Small): 80,000JPY

*All prices are Tax excl.



APMC2026 official website

Application
DEADLINE
October
6 (Tue.),
2026

Logo Placement on Novelties (per item)

Your logo will be featured on promotional items distributed to attendees, as well as on signage at the reception and banquet venues.

- Conference bag: 150,000JPY
- Ballpoint pen: 100,000JPY
- Coffee break signboard: 100,000JPY
- Reception signboard: 100,000JPY
- Banquet signboard: 100,000JPY
- Lanyard: 150,000JPY

*All prices are Tax excl.

Application
DEADLINE
September
8 (Tue.),
2026